

N-Channel NexFET™ Power MOSFET

Check for Samples: [CSD16414Q5](#)

FEATURES

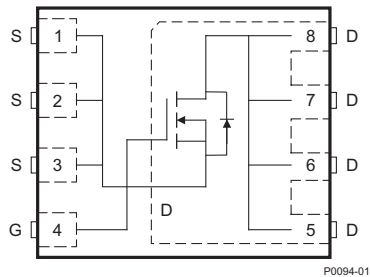
- Ultra Low Qg and Qgd
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5mm x 6mm Plastic Package

APPLICATIONS

- Point-of-Load Synchronous Buck Converter for Applications in Networking, Telecom and Computing Systems
- Optimized for Synchronous FET Applications

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.

Top View


PRODUCT SUMMARY

V_{DS}	Drain to Source Voltage	25	V
Q_g	Gate Charge Total (4.5V)	16.6	nC
Q_{gd}	Gate Charge Gate to Drain	4.4	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5V$	2.1 mΩ
		$V_{GS} = 10V$	1.5 mΩ
$V_{GS(th)}$	Threshold Voltage	1.6	V

ORDERING INFORMATION

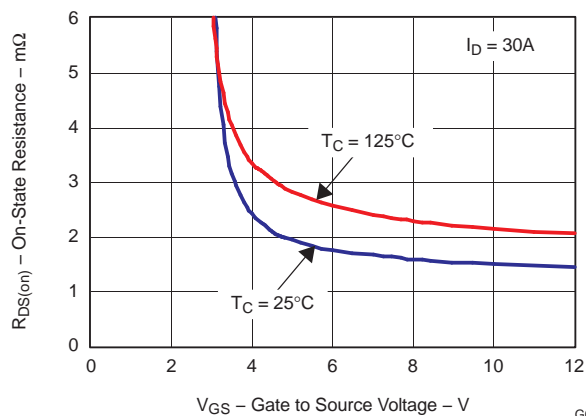
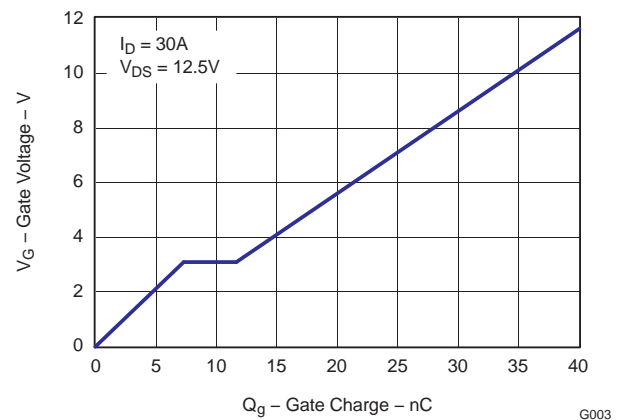
Device	Package	Media	Qty	Ship
CSD16414Q5	SON 5 x 6 Plastic Package	13-inch reel	2500	Tape and Reel

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	25	V
V_{GS}	Gate to Source Voltage	+16 / -12	V
I_D	Continuous Drain Current, $T_C = 25^\circ\text{C}$	100	A
	Continuous Drain Current ⁽¹⁾	34	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ ⁽²⁾	213	A
P_D	Power Dissipation ⁽¹⁾	3.2	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Avalanche Energy, single pulse $I_D = 100\text{A}, L = 0.1\text{mH}, R_G = 25\Omega$	500	mJ

(1) $R_{\theta JA} = 39^\circ\text{C/W}$ on 1in² Cu (2 oz.) on 0.060" thick FR4 PCB.

(2) Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

 $R_{DS(on)}$ vs V_{GS}

Gate Charge


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ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

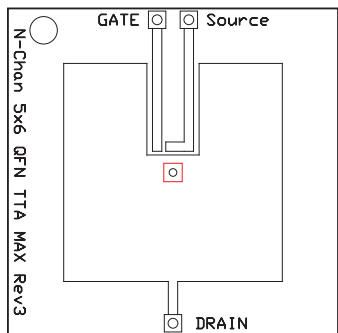
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
B _V DSS	Drain to Source Voltage	V _{GS} = 0V, I _D = 250μA	25			V
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 20V			1	μA
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = +16/-12V			100	nA
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.3	1.6	2	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 4.5V, I _D = 30A		2.1	2.6	mΩ
		V _{GS} = 10V, I _D = 30A		1.5	1.9	mΩ
g _{fs}	Transconductance	V _{DS} = 15V, I _D = 30A		138		S
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V, V _{DS} = 12.5V, f = 1MHz	2810	3650		pF
C _{OSS}	Output Capacitance		2040	2650		pF
C _{RSS}	Reverse Transfer Capacitance		140	180		pF
R _g	Series Gate Resistance	V _{DS} = 12.5V, I _D = 30A	1.4	2.8		Ω
Q _g	Gate Charge Total (4.5V)		16.6	21		nC
Q _{gd}	Gate Charge Gate to Drain		4.4			nC
Q _{gs}	Gate Charge Gate to Source		7.3			nC
Q _{g(th)}	Gate Charge at V _{th}		4.5			nC
Q _{OSS}	Output Charge	V _{DS} = 13.5V, V _{GS} = 0V	40			nC
t _{d(on)}	Turn On Delay Time	V _{DS} = 12.5V, V _{GS} = 4.5V, I _D = 30A R _G = 2Ω	15			ns
t _r	Rise Time		24			ns
t _{d(off)}	Turn Off Delay Time		18.4			ns
t _f	Fall Time		11.1			ns
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _S = 30A, V _{GS} = 0V	0.81	1		V
Q _{rr}	Reverse Recovery Charge	V _{dd} = 13.5V, I _F = 30A, di/dt = 300A/μs	44			nC
t _{rr}	Reverse Recovery Time	V _{dd} = 13.5V, I _F = 30A, di/dt = 300A/μs	35			ns

THERMAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

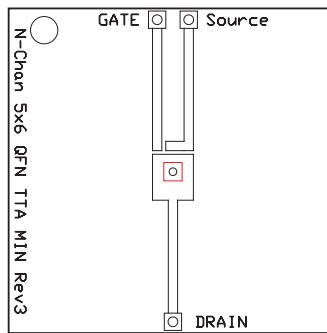
PARAMETER		MIN	TYP	MAX	UNIT
R _{θJC}	Thermal Resistance Junction to Case ⁽¹⁾			1.1	°C/W
R _{θJA}	Thermal Resistance Junction to Ambient ^{(1) (2)}			50	°C/W

- (1) R_{θJC} is determined with the device mounted on a 1 inch square 2 oz. Cu pad on a 1.5 × 1.5 in 0.060 inch thick FR4 board. R_{θJC} is specified by design while R_{θJA} is determined by the user's board design.
- (2) Device mounted on FR4 Material with 1 inch² of 2 oz. Cu.



Max $R_{\theta JA} = 50^{\circ}\text{C/W}$
when mounted on
1inch² of 2 oz. Cu.

M0137-01



Max $R_{\theta JA} = 122^{\circ}\text{C/W}$
when mounted on
minimum pad area of 2
oz. Cu.

M0137-02

TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^{\circ}\text{C}$ unless otherwise stated)

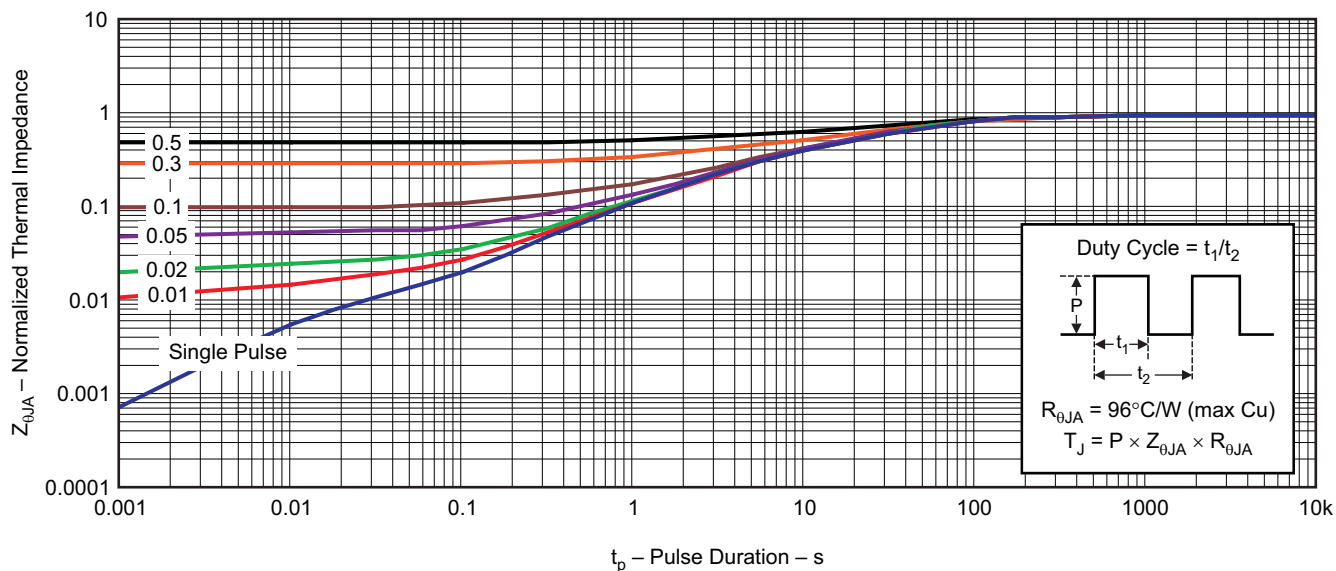


Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

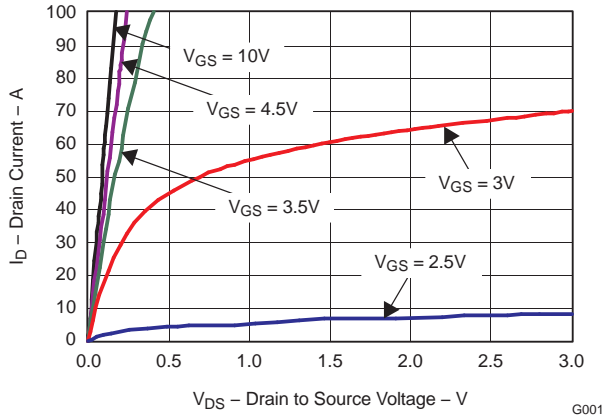


Figure 2. Saturation Characteristics

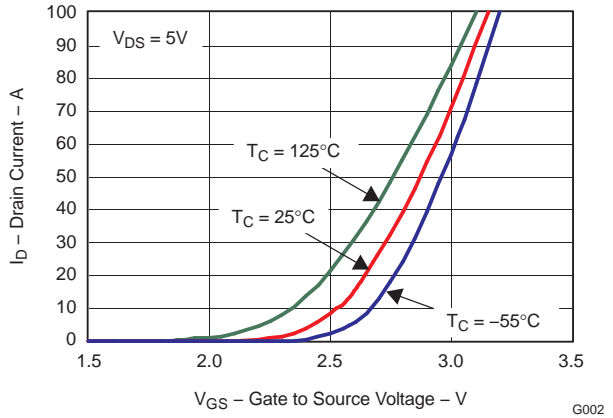


Figure 3. Transfer Characteristics

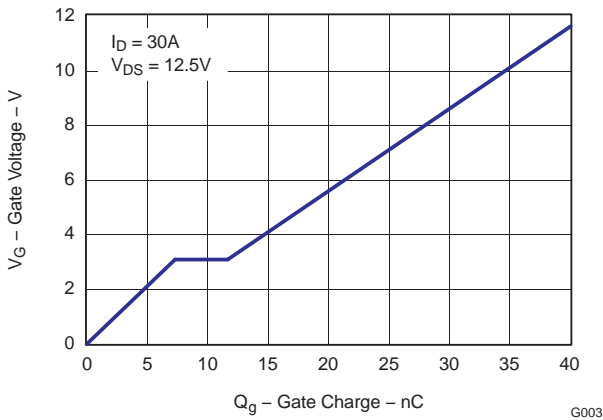


Figure 4. Gate Charge

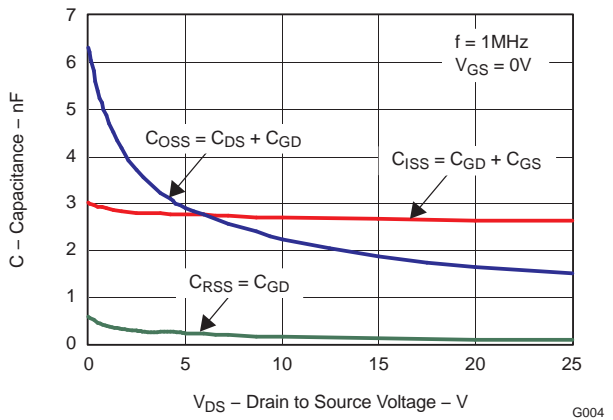


Figure 5. Capacitance

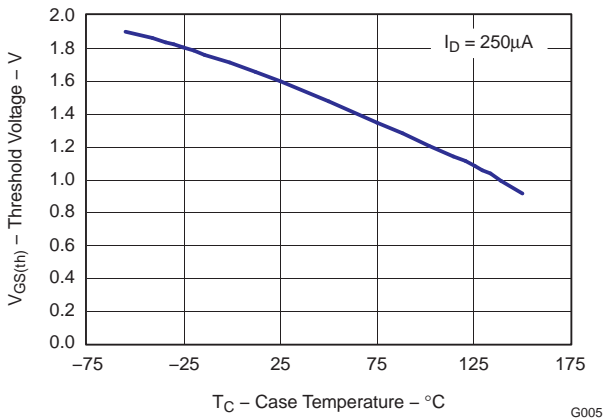


Figure 6. Threshold Voltage vs. Temperature

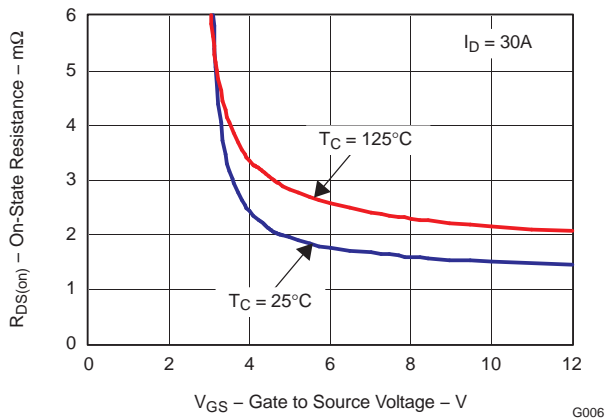


Figure 7. On Resistance vs. Gate Voltage

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

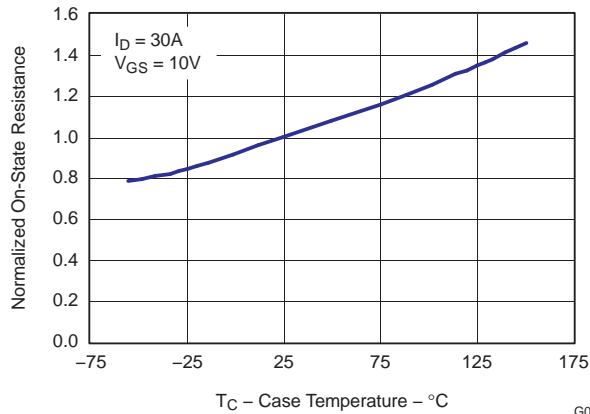


Figure 8. On Resistance vs. Temperature

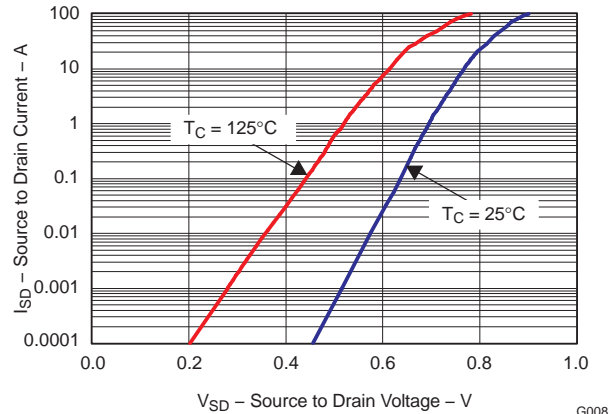


Figure 9. Typical Diode Forward Voltage

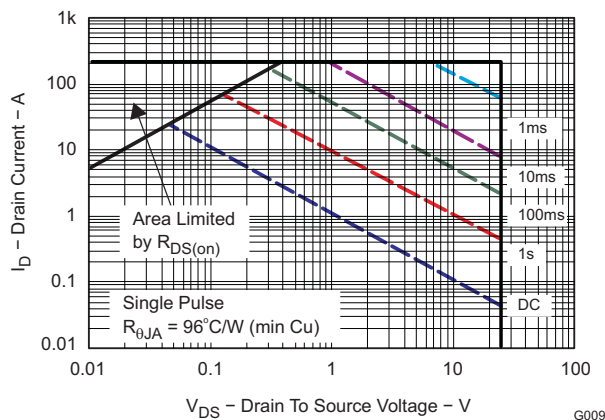


Figure 10. Maximum Safe Operating Area

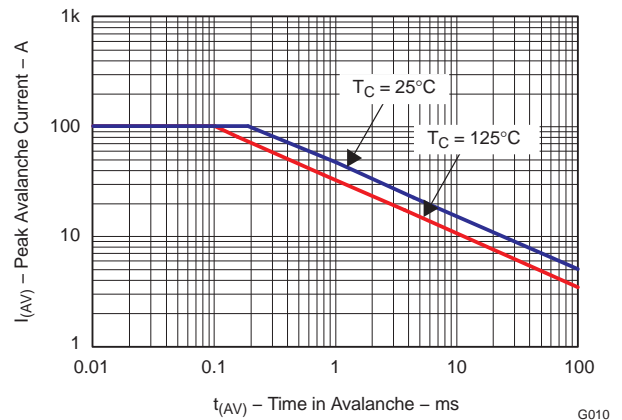


Figure 11. Single Pulse Unclamped Inductive Switching

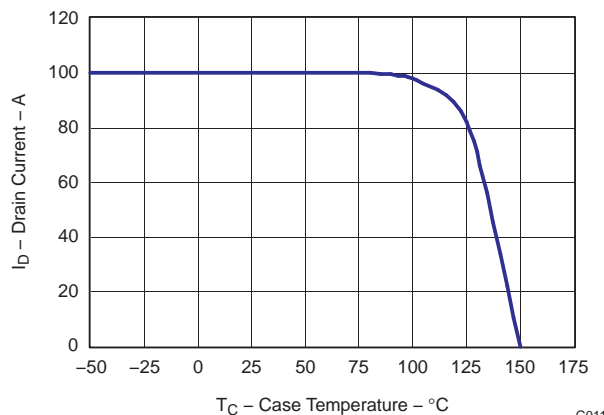
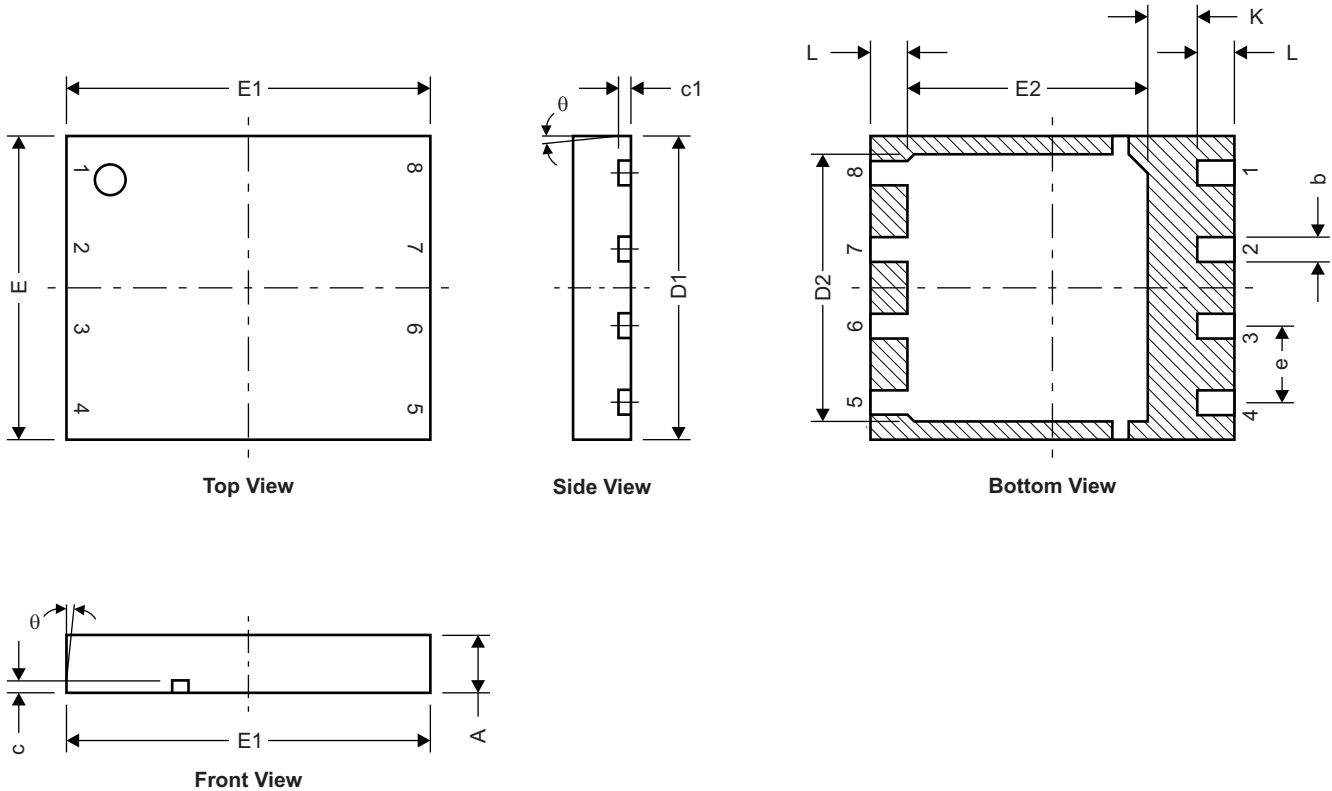


Figure 12. Maximum Drain Current vs. Temperature

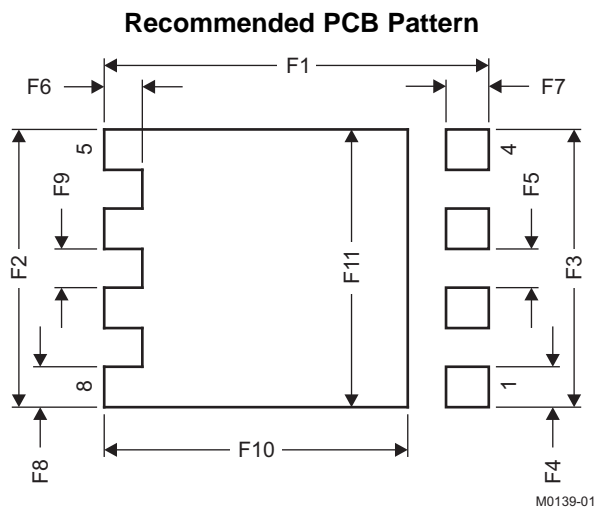
MECHANICAL DATA

Q5 Package Dimensions



M0140-01

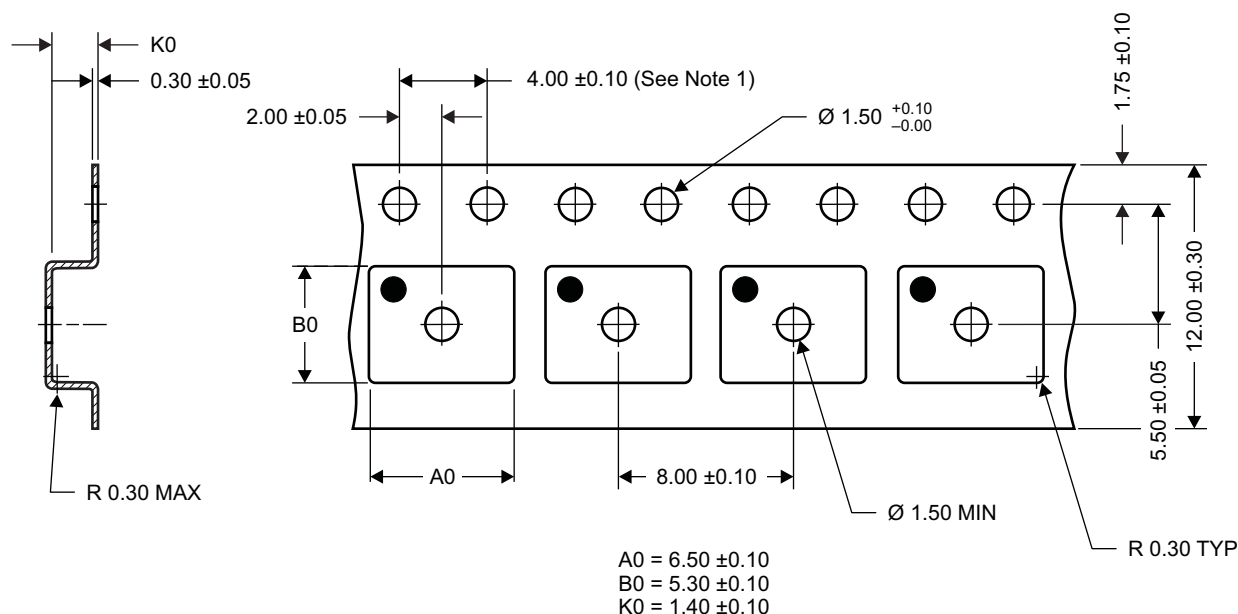
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.950	1.050	0.037	0.039
b	0.360	0.460	0.014	0.018
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
D1	4.900	5.100	0.193	0.201
D2	4.320	4.520	0.170	0.178
E	4.900	5.100	0.193	0.201
E1	5.900	6.100	0.232	0.240
E2	3.920	4.12	0.154	0.162
e	1.27 TYP		0.050	
K	0.760		0.030	
L	0.510	0.710	0.020	0.028
θ	0.00			



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.460	4.560	0.176	0.180
F3	4.460	4.560	0.176	0.180
F4	0.650	0.700	0.026	0.028
F5	0.620	0.670	0.024	0.026
F6	0.630	0.680	0.025	0.027
F7	0.700	0.800	0.028	0.031
F8	0.650	0.700	0.026	0.028
F9	0.620	0.670	0.024	0.026
F10	4.900	5.000	0.193	0.197
F11	4.460	4.560	0.176	0.180

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

Q5 Tape and Reel Information



M0138-01

Notes:

- 10 sprocket hole pitch cumulative tolerance ± 0.2
- Camber not to exceed 1mm IN 100mm, noncumulative over 250mm
- Material: black static dissipative polystyrene
- All dimensions are in mm (unless otherwise specified)
- Thickness: 0.30 ± 0.05 mm
- MSL1 260°C (IR and Convection) PbF Reflow Compatible

REVISION HISTORY

Changes from Original (August 2009) to Revision A	Page
• Deleted the Package Marking Information section	7

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CSD16414Q5	Active	Production	VSON-CLIP (DQH) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD16414
CSD16414Q5.Z	Active	Production	VSON-CLIP (DQH) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD16414

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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